

What is claimed is:

- 1 1. An electronics assembly comprising:
2 a heat generating component;
3 a heat sink positioned to define a gap between said heat
4 generating component and said heat sink;
5 at least one pre-cured thermal adhesive member positioned
6 within said gap creating a physical barrier between said heat generating
7 component and said heat sink; and
8 a post-cured thermal adhesive member filling said gap.
- 1 2. An electronics assembly as described in claim 1 wherein
2 said heat generating component is an electrical component.
- 1 3. An electronics assembly as described in claim 1 wherein
2 said at least one pre-cured thermal adhesive member is formed using droplets of
3 thermal adhesive.
- 1 4. An electronics assembly as described in claim 1 wherein
2 said at least one pre-cured thermal adhesive member is affixed to said heat
3 generating component prior to assembly.
- 1 5. An electronics assembly as described in claim 1 wherein
2 said at least one pre-cured thermal adhesive member is affixed to said heat sink
3 prior to assembly.
- 1 6. An electronics assembly as described in claim 1 further
2 comprising:
3 a substrate; and
4 at least one clamping mechanism attaching said substrate to said
5 heat sink.
- 1 7. An electronics assembly as described in claim 1 wherein
2 said heat sink is a metal case.

1 8. An electronics assembly as described in claim 1 wherein
2 said heat sink includes a heat rail.

1 9. An electronics assembly as described in claim 1 wherein
2 said heat sink includes a thermally conductive bracket.

1 10. An electronics assembly as described in claim 1 wherein
2 said at least one pre-cured thermal adhesive member includes dots of equal
3 height.

1 11. A method of applying thermal adhesive to an electronics
2 assembly comprising:

3 forming a plurality of pre-cure thermal adhesive members;
4 curing said plurality of pre-cure thermal adhesive members;
5 applying a post-cure thermal adhesive;
6 assembling an electronics assembly including a heat generating
7 component and a heat sink such that said plurality of pre-cure thermal adhesive
8 members and said post-cure thermal adhesive are positioned within a gap
9 formed between said heat generating component and said heat sink; and
10 curing said post-cure thermal adhesive.

1 12. A method as described in claim 11 wherein said plurality
2 of pre-cure thermal adhesive members are formed on said heat generating
3 component.

1 13. A method as described in claim 11 wherein said plurality
2 of pre-cure thermal adhesive members are formed in said heat sink.

1 14. A method as described in claim 11 wherein said heat
2 generating component is an electrical component.

1 15. A method as described in claim 11 wherein said forming
2 a plurality of pre-cure thermal adhesive members includes forming droplets of
3 pre-cure thermal adhesive.

1 16. A method as described in claim 11 wherein said post-cure
2 thermal adhesive is applied to said heat generating component.

1 17. A method as described in claim 11 wherein said post-cure
2 thermal adhesive is applied to said heat sink.

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